



REVISIONS			
REV	DESCRIPTION	DATE	APPROVED
A	Initial Revision	04JUN13	B.HURST
B	-ADDED DC BLOCK CAP FOR RF SWITCH PORTS. -FIXED INPUT LOGIC FOR RF SWITCHES.	27JUN13	B.HURST
C	-ADDED EXT PA AND REPLACED OBSOLETE EXT. LNA	14JAN14	B.HURST
D	SEPARATED TX/RX PATH	3FEB14	B.HURST
E	ADDED RF SWITCHES TO SEPARATE TX/RX PATH	13FEB14	B.HURST
F	REDUCED PAD SIZE OF ZL70251 TO 4 MILS AND LIMITED TRACE 3 MILS ENTERING PAD.	01MAY14	B.HURST
G	CHANGED CMOS RF SWITCHES TO GAAS RF SWITCHES.	10JUN14	B.HURST

DRILL CHART: TOP to BOTTOM				
ALL UNITS ARE IN MILS				
FIGURE	SIZE	TOLERANCE	PLATED	QTY
⊙	8.0	+0.0/-0.0	PLATED	226
•	16.0	+0.0/-0.0	PLATED	8
⊞	40.0	+0.0/-0.0	PLATED	59
•	23.6	+2.0/-0.0	NON-PLATED	4
Ⓟ	110.0	+0.0/-0.0	NON-PLATED	10

0.5 OZ. CU		TOP - SIGNAL
1.0 OZ. CU	0.011 INCH CORE	LAYER2 - GND PLANE
	0.015 INCH PREPREG	
0.5 OZ. CU		LAYER3 - VSUP2/SIGNAL
0.5 OZ. CU	0.004 INCH CORE	LAYER4 - VUSP1/SIGNAL
	0.015 INCH PREPREG	
1.0 OZ. CU		LAYER5 - PWR PLANE (+3.3V)
0.5 OZ. CU	0.011 INCH CORE	BOTTOM - SIGNAL

CATEGORY	DESCRIPTION
COPPER WEIGHT	1.0 OZ. ON LAYER 2 AND 5; 0.5 OZ. ALL OTHER LAYERS
SOLDERMASK	BOTH SIDES WITH LPI GREEN OVER BARE COPPER
HOLE TOLERANCES	.005 INCH OF TRUE DIAMETER. REGISTRATION .005
DIMENSIONS	INCH
SUBSTRATE MATERIAL	370HR LAMINATE
FINISH	ENIG
PCB THICKNESS	0.062 +/- .004 INCHES
IPC SPECS	IPC-6012 TYPE 3 CLASS 2
SILKSCREEN	COMPONENT AND CIRCUIT SIDE WITH WHITE EPOXY INK. DO NOT USE INKJET PROCESS FOR SILKSCREEN.
VIAS	REMOVE SOLDERMASK FROM VIA IF ONE SIDE DOES NOT HAVE SOLDERMASK.

UNLESS OTHERWISE SPECIFIED	SIGNATURES	DATE	MICROSEMI CORP. 15822 Bernardo Center Drive, Suite B San Diego, CA 92127			
DIMENSIONS ARE IN INCHES TOLERANCES ON: 2 PL DECIMALS + 3 PL DECIMALS + ANGLES + FRACTIONS +			ZLE70251ADK CSP ADK BASE251			
			SIZE	FSCM NO	DWG NO	
			SCALE		SHEET 1 of 1	